

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

Technical Contact:

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Implementation of change:

Expected 1st Device Shipment Date: 2011/08/01

Earliest Year/Work Week of Changed Product: 1120

Change Type Description: Alternate Assembly Site Location / Qualification

Description of Change (From): 16-lead MDIP package assembled and tested at Kodenshi SY Corp, China.

Description of Change (To): 16-lead MDIP package assembled and tested at SiTEC Semiconductor Ltd (D.G.),China. Standardization of product marking with line 1 marked as FSC logo + plant code + bi-weekly date code + trace code and line 2 marked as device ID.

Reason for Change : Fairchild plans to exit from Kodenshi SY Corp, China and start assembly & test at SiTEC Semiconductor Ltd, China. This change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products. This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days. Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

Qual/REL Plan Number(s): Q20100666, Q20110002

Qualification :

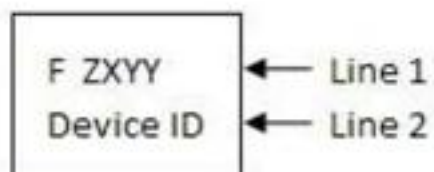
16-lead MDIP products assembled and tested by Sitec Semiconductor Ltd (D.G) have successfully passed Fairchild's reliability qualification requirements and are therefore approved for production.

Change From

Bill of Materials:

Item	MDIP-16L Details
Assembly Site	Kodenshi SY Corp
Wire	Au 1.0 mil
Die Attach	SK-5DK
Leadframe	Copper
Mold Compound	SI7200DM

Existing product marking format:



Remark:

F : Fairchild logo

Z : Plant code

X : Year code

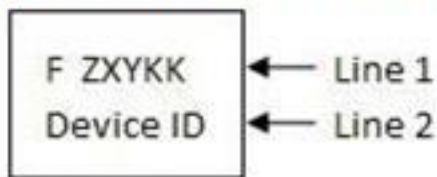
YY : Weekly date code

Change To

Bill of Materials:

Item	MDIP-16L Details
Assembly Site	Sitec Semiconductor Ltd (D.G)
Wire	Au 1.0 mil
Die Attach	Yiz-8511F
Leadframe	Copper
Mold Compound	ELER-8-560

Standardization of product marking format:



Remark:

F : Fairchild logo

Z : Plant code

X : Year code

Y : Weekly date code

KK : Two digit trace code

Results/Discussion for Qual Plan Number(s): Q20100666

Test: (High Temperature Op Life) | Conditions: 70C | Standard:

Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20100666AAHTOL	KA7500B	0/77			
			0/77		
				0/77	

Test: (High Temperature Op Life) | Conditions: 85C | Standard:

Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20100666BAHTOL	KA7500C	0/77			
			0/77		
				0/77	

Test: (High Temperature Storage Life) | Conditions: 150C | Standard: JESD22-A103

Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20100666AAHTSL	KA7500B	0/77			
			0/77		
				0/77	
Q20100666BAHTSL	KA7500C	0/77			
			0/77		
				0/77	

Test: (Highly Accelerated Stress Test) | Conditions: 85%RH, 130C, 8V | Standard: JESD22-A110

Lot	Device	96-HOURS	Failure Code
Q20100666AAHAST1	KA7500B	0/77	
Q20100666BAHAST1	KA7500C	0/77	

Test: (Temperature Cycle) | Conditions: -65C, 150C | Standard: JESD22-A104

Lot	Device	100-CYCLES	500-CYCLES	Failure Code
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Q20100666AATMCL1	KA7500B	0/77		
Q20100666AATMCL1	KA7500B		0/77	
Q20100666BATMCL1	KA7500C	0/77		
Q20100666BATMCL1	KA7500C		0/77	

Results/Discussion for Qual Plan Number(s): Q20110002

Test: (High Temperature Op Life) Conditions: 100C Standard:					
Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20110002AAHTOL	FAN7621N	0/77			
			0/77		
				0/77	

Test: (High Temperature Reverse Bias) Conditions: 125C, 480V Standard: JESD22-A108					
Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20110002AAHTRB		0/77			
			0/77		
				0/77	

Test: (High Temperature Storage Life) Conditions: 150C Standard: JESD22-A103					
Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20110002AAHTSL		0/77			
			0/77		
				0/77	

Test: (Highly Accelerated Stress Test) Conditions: 85%RH, 110C, 12V Standard: JESD22-A110					
Lot	Device	96-HOURS	264-HOURS	Failure Code	
Q20110002AAHAST2	FAN7621N	0/77			
Q20110002AAHAST2	FAN7621N		0/77		

Test: (Temperature Cycle) Conditions: -65C, 150C Standard: JESD22-A104					
Lot	Device	100-CYCLES	500-CYCLES	Failure Code	
Q20110002AATMCL1	FAN7621N	0/77			
Q20110002AATMCL1	FAN7621N		0/77		

Product Id Description :

Affected FSIDs :

FAN7621N	KA3525A	KA7500B
KA7500C		